X1#

Final Assembly
Test (Consumer)

FATP AXI Platform

The X1# is a high-quality, high-resolution, low-footprint and portable x-ray inspection system for final assembly inspection and advanced failure analysis applications. Featuring the Teach&Go function of the Matrix Image Processing Software (MIPS), the X1# is an easy to learn and easy to use system designed to enable the fastest possible inspection program creation. The above feautres make this platform the industry leading solution for automated assembly inspection tasks. The small footprint allows passage through a standard door width.

The X1# system is available with Transmission (2D) imaging with SFT™ to enable superior image quality with background removal, resulting in outstanding repeatability of the measurement values. An advanced algorithm library is part of the standard image processing package. Customized algorithms are available upon request.

Inspection & Process Software

- PC-Station with multi-core processor setup
- Windows 10 platform
- MIPS 5 Inspection Platform
  - Advanced algorithm library
  - CAD import for automatic inspection list generation
  - Automatic Tree Classification (ATC) for Auto-Rule-Generation
  - Offline programming for AXI program generation & simulation, tuning and defect reference catalogue
- Verification & Process control
  - MIPS Verify link with closed loop repair
  - MIPS Process with real time SPC

Features and Benefits

- Offline AXI system
- Microfocus X-ray tube (sealed tube / maintenance free)
- Digital CMOS flatpanel detector
- Automatic grey-level and geometrical calibration
- Barcode scanner for serial number and product type selection
- Full product traceability via various Industry 4.0 MES-Interfaces
- IPC-CFX ready

Nordson MATRIX

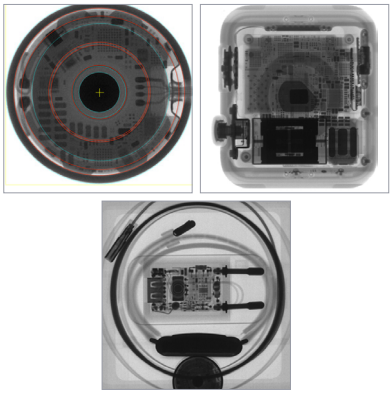
X1#

Applications

Electronic components and solder joint

A unique advanced algorithm library is available for electronic applications, specifically for final assembly tasks and solder-joint inspection for PCB assemblies.

- Assembly completion test
- Specific BGA and QFN algorithm
- Final production quality test
- All standard SMDs and THT/PTH components



Specifications

Facilities	
Dimensions:	1330 mm (H) x 850 mm (W) x 880 mm (D)
Weight:	731 kg
Safe Operating Temperature:	15° - 32 °C optimal 20° - 25° C
Power Consumption	Max. 6kW
Line Voltage:	220 VAC, 50/60 Hz 3 phase, 16 A
Air:	6 Bar

X-ray Image Chain	
X-ray Source (sealed tube)	
Energy:	120kV or 130 kV/40 W
Grey resolution:	14 Bit
CMOS Flatpanel Detector	50 µm pixel size (5 MPix)

Options
Barcodereader

Inspection features	
Max. carrier size:	94 mm x 54 mm
Max. inspection area:	50 mm x 50 mm
Resolution	down to 10 µm /pix

For more information, speak with your Nordson MATRIX representative.

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